

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DKT. NO. 501.36636CC3	SERIAL NO. TBD
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		APPLICANT KONDO, et al.	
		FILING DATE April 16, 2004	GROUP 2812

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
BT	AA	5,858,813	1-12-99	Scherber, et al.	438	693
	AB	5,866,031	2-2-99	Carpio, et al.	252	79.1
	AC	5,840,629	11-24-98	Carpio	438	692
	AD	5,783,489	7-21-98	Kaufman, et al.	438	692
	AE	5,759,917	6-2-98	Grover	438	690
	AF	5,733,176	3-31-98	Robinson, et al.	451	41
	AG	5,695,660	12-9-97	Litvak	216	85
	AH	5,676,760	10-14-97	Aoki, et al.	134	1.3
BT	AI	4,944,836	6-90	Beyer, et al.		
	AJ					
	AK					
	AL					

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AM						
	AN						
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

BT	AU	"Pattern Geometry Effects in the Chemical-Mechanical Polishing of Inlaid Copper Structures", J. Electrochem. Soc., vol. 141, p. 2842-2848, October 10, 1994.
BT	AV	"An Examination of Slurry for Wiring Metal's Chemical-Mechanical Polishing", vol. 41, p. 35-37, June 1997 (in Japanese)
	AW	"Semiconductor International", Semiconductor World, p. 171-172, May 1995 (in Japanese)
	AX	"Electrochemical Potential Measurements during the Chemical-Mechanical Polishing of Copper Thin Films", J.E. Electrochem. Soc., vol. 142, July 7, 1995 p. 2379-2385.
	AY	"Chemical Mechanical Polishing of Copper using a Slurry composed of glycine and hydrogen peroxide", CMP-MIC Conferences 1996 ISMIC, February 22-23, 1996, CMP p. 119-123.
BT	AZ	Kashiwagi, The Science of CMP (1997), p. 299-300.
Examiner /Binh Tran/		Date Considered 06/05/2006

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**INFORMATION DISCLOSURE
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501.36636003

SERIAL NO.

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APPLICANT
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FILING DATE
April 16, 2004

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2812

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
BT	5,770,095	06/1998	Sasaki, et al			
	6,117,783	09/2000	Small, et al.			
	6,001,269	12/1999	Suthuraman, et al.			
	5,932,486	08/1999	Cook, et al.			
	5,875,507	03/1999	Stephens			
	5,972,792	10/1999	Hudson			
BT	5,575,885	1996	Hirabayashi, et al.			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation/ ABSTRACT	
						YES	NO
BT	07-233485	1995	Japan			X	
BT	07-161669	1995	Japan			X	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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DATE CONSIDERED 06/05/2006

EXAMINER: Initial if citation is considered, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

(Form PTO-1449 [6-4])